





#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on) max</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
-40V	11mΩ @ V <sub>GS</sub> = -10V	-10.1A
-40 V	15mΩ @ V <sub>GS</sub> = -4.5V	-8.8A

#### **Features and Benefits**

- 100% Unclamped Inductive Switch (UIS) test in production
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Available

#### **Description**

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

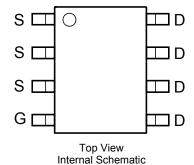
## Applications

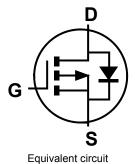
- DC-DC Converters
- Power management functions
- Analog Switch

#### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (approximate)







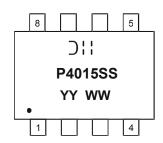
Ordering Information (Note 4 & 5)

Ī	Part Number	Qualification	Case	Packaging
	DMP4015SSSQ-13	Automotive	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_grade\_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



O!! = Manufacturer's Marking
P4015SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	-40	V		
Gate-Source Voltage		$V_{GSS}$	±25	V	
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-9.1 -7.2	Α
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-7.8 -6.2	Α
Continuous Drain Current (Note 7) V <sub>GS</sub> = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-10.1 -8	Α
Continuous Drain Current (Note 7) V <sub>GS</sub> = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-8.8 -7	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	-100	Α		
Avalanche Current (Note 8)	I <sub>AS</sub>	-22	Α		
Avalanche Energy (Note 8)	Eas	242	mJ		

### **Thermal Characteristics**

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 6)	$P_{D}$	1.45	W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>0JA</sub>	88	°C/W
Total Power Dissipation (Note 7)	P <sub>D</sub>	1.82	W
Thermal Resistance, Junction to Ambient (Note 7)	R <sub>0JA</sub>	70	°C/W
Thermal Resistance, Junction to Case (Note 7)	$R_{ heta Jc}$	7.6	°C/W
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-55 to +150	°C

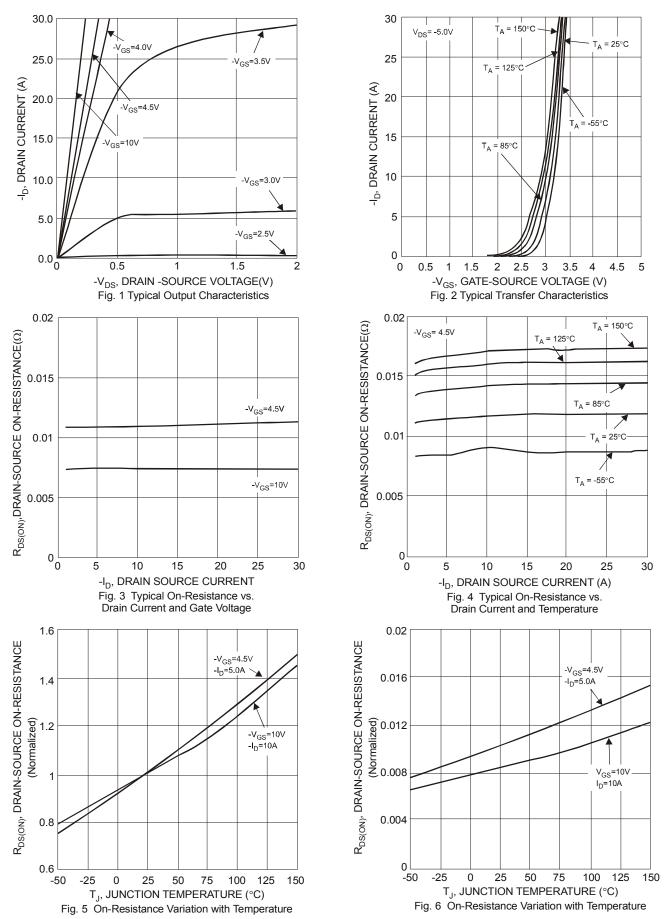
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)	Syllibol	IVIIII	Тур	IVIAX	Ullit	rest condition	
Drain-Source Breakdown Voltage	D\/	-40	_	l _	V	\/ = 0\/  _= 250uA	
	BV <sub>DSS</sub>					$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			-1	μA	$V_{DS} = -40V$ , $V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	$V_{GS(th)}$	-1.5	-2	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance		_	7	11	mΩ	$V_{GS} = -10V, I_D = -9.8A$	
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	_	9	15	11122	$V_{GS} = -4.5V$ , $I_{D} = -9.8A$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	26	_	S	V <sub>DS</sub> = -20V, I <sub>D</sub> = -9.8A	
Diode Forward Voltage (Note 6)	V <sub>SD</sub>	_	-0.7	-1	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>	_	4234	_		V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V f = 1MHz	
Output Capacitance	Coss	_	1036	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	526	_		I = IIVIPZ	
Gate Resistance	R <sub>G</sub>	_	7.77	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	47.5	_			
Gate-Source Charge	Q <sub>gs</sub>	_	14.2	_	nC	$V_{DS} = -20V, V_{GS} = -5V$	
Gate-Drain Charge	Q <sub>gd</sub>	_	13.5	_		$I_D = -9.8A$	
Turn-On Delay Time	t <sub>D(on)</sub>	_	13.2				
Turn-On Rise Time	t <sub>r</sub>	_	10		20	$V_{GS} = -10V$ , $V_{DD} = -20V$ , $R_{G} = 6\Omega$ ,	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	302.7	_	ns	$I_D = -1A, R_L = 20\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	_	137.9	_			

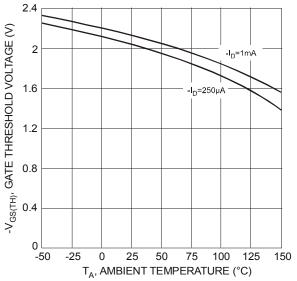
Notes:

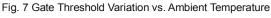
- 6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate 8 .UIS in production with L = 1mH,  $T_J$  = +25°C
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to production testing.

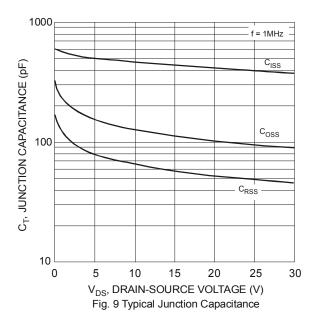


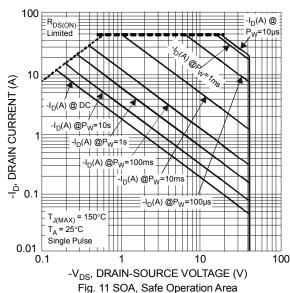


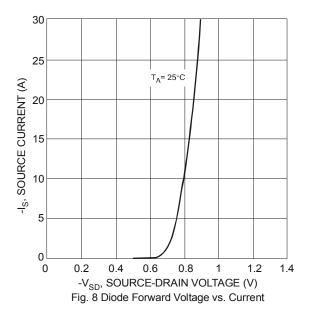


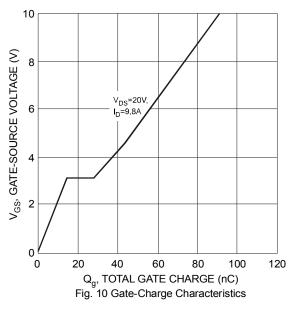


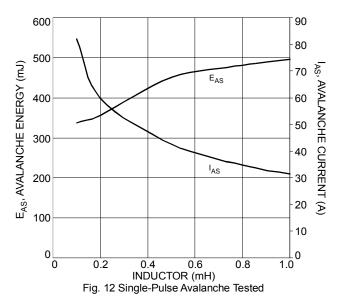




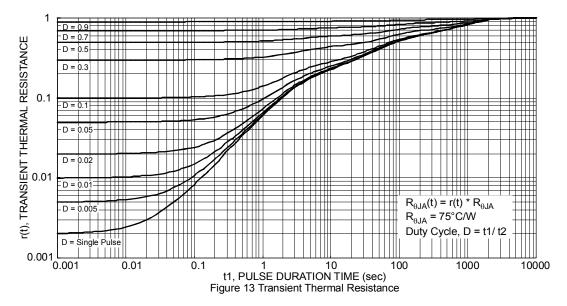






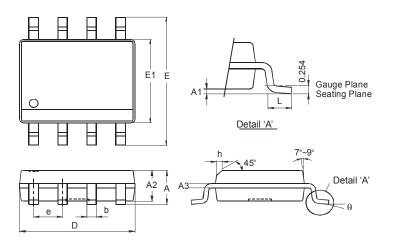






## **Package Outline Dimensions**

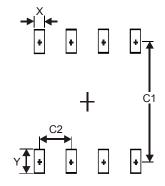
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8						
Dim	Min	Max				
Α	-	1.75				
A1	0.10	0.20				
A2	1.30	1.50				
А3	0.15	0.25				
b	0.3	0.5				
D	4.85	4.95				
Е	5.90	6.10				
E1	3.85	3.95				
е	1.27 Typ					
h	-	0.35				
L	0.62	0.82				
θ	0°	8°				
All Dimensions in mm						

## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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